

11-21-2003  
102606465

To the Honorable Commissioner of Patents and Trademarks

and original documents or copy thereof.

1. Name of conveying party(ies):

SCP IP, INC.

11-18-03

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of Conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other:

Execution Date: March 14, 2003

2. Name and address of receiving party(ies):

Name: COMERICA BANK, successor by merger to  
Comerica Bank-California  
Address: 9920 S. LA CIENEGA BLVD., SUITE 1401  
City: INGLEWOOD State: CA Zip: 90301

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

If this Document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/478,094	09/574,790	09/727,661
09/930,009	10/074,516	10/163,441

Patent No.(s)

4,577,650	4,633,893	4,738,272
4,740,249	4,778,532	4,795,497
4,856,544	4,899,767	4,911,761
4,917,123	4,984,597	5,383,484
5,972,123	6,032,682	6,132,522
6,143,087	6,165,912	6,245,158
6,261,845	6,348,101	6,378,544
6,491,763	6,495,099	

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Erin O'Brien  
Internal Address: GRAY CARY WARE & FREIDENRICH  
4365 Executive Drive, Suite 1100  
San Diego, CA 92121-2133

6. Total number of applications and patents involved: 29

2003 NOV 18 PM 2:52  
OPR/FINANCE

7. Total fee (37 CFR 3.41) . . . . . \$ 1,160.00

Enclosed

8. Deposit account number:

Please debit any underpayment or credit any overpayment to the above deposit account.

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Erin O'Brien  
Name of Person Signing

November 18, 2003  
Date

Total number of pages comprising cover sheet: [ 13 ]

OMB No. 0651-0011 (exp. 4/94)

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

U.S. Patent and Trademark Office  
Office of Public Records  
Crystal Gateway 4, Room 335

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## INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement (the "Agreement") is made as of March 14, 2003, by and between SCP IP, INC., a Delaware corporation ("Grantor"), and COMERICA BANK-CALIFORNIA ("Secured Party").

### RECITALS

A. Secured Party has made loans to SCP GLOBAL TECHNOLOGIES, INC. and SCP U.S., INC. (each, a "Borrower"; collectively, the "Borrowers"), which are affiliates of Grantor, pursuant to a Loan and Security Agreement of even date herewith, as amended from time to time (the "Loan and Security Agreement"). Grantor expects to derive economic benefit from Secured Party's doing so and has entered into an Unconditional Guaranty (as amended from time to time, the "Guaranty") and a Third Party Security Agreement (as amended from time to time, the "Third Party Security Agreement"), both dated of even date herewith. The Guaranty, the Third Party Security Agreement, and the Loan and Security Agreement are collectively referred to herein as the "Loan Agreements"). All capitalized terms used herein without definition shall have the meanings ascribed to them in the Loan Agreements.

B. Secured Party is willing to make credit extensions to Borrowers, but only upon the condition, among others, that Grantor shall grant to Secured Party a security interest in all of Grantor's right title, and interest in, to and under all of the Collateral whether presently existing or hereafter acquired.

NOW, THEREFORE, THE PARTIES HERETO AGREE AS FOLLOWS:

1. Grant of Security Interest. As collateral security for the prompt and complete payment and performance of all of Grantor's present or future indebtedness, obligations and liabilities to Secured Party, Grantor hereby grants a security interest and mortgage to Secured Party, as security, in and to Grantor's entire right, title and interest in, to and under all of its intellectual property, including without limitation the following (all of which shall collectively be called the "Collateral"):

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work or authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the "Copyrights");

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights which may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including without limitation improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the "Patents");

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the "Trademarks");

(f) Any and all claims for damages by way of past, present and future infringement of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(g) All licenses or other rights to use any of the Copyrights, Patents or Trademarks, and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(h) All amendments, renewals and extensions of any of the Copyrights, Trademarks or Patents; and

(i) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. Covenants and Warranties. Grantor represents, warrants, covenants and agrees as follows:

(a) Grantor is now the sole owner of the Collateral, except for licenses granted by Grantor to its customers in the ordinary course of business;

(b) Except as set forth in the Schedule, Grantor's rights as a licensee of intellectual property do not give rise to more than five percent (5%) of its gross revenue in any given month, including without limitation revenue derived from the sale, licensing, rendering or disposition of any product or service;

(c) Performance of this Agreement does not conflict with or result in a breach of any agreement to which Grantor is party or by which Grantor is bound;

(d) During the term of this Agreement, Grantor will not transfer or otherwise encumber any interest in the Collateral, except for licenses granted by Grantor in the ordinary course of business or as set forth in this Agreement;

(e) To its knowledge, each of the Patents is valid and enforceable, and no part of the Collateral has been judged invalid or unenforceable, in whole or in part, and no claim has been made that any part of the Collateral violates the rights of any third party;

(f) Grantor shall deliver to Secured Party within thirty (30) days of the last day of each fiscal quarter, a report signed by Grantor, in form reasonably acceptable to Secured Party, listing any applications or registrations that Grantor has made or filed in respect of any patents, copyrights or trademarks and the status of any outstanding applications or registrations. Grantor shall promptly advise Secured Party of any material change in the composition of the Collateral, including but not limited to any subsequent ownership right of the Grantor in or to any Trademark, Patent or Copyright not specified in this Agreement;

(g) Grantor shall (i) protect, defend and maintain the validity and enforceability of the Trademarks, Patents and Copyrights (ii) use its best efforts to detect infringements of the Trademarks, Patents and Copyrights and promptly advise Secured Party in writing of material infringements detected and (iii) not allow any Trademarks, Patents or Copyrights to be abandoned, forfeited or dedicated to the public without the written consent of Secured Party, which shall not be unreasonably withheld;

(h) Grantor shall apply for registration on an expedited basis (to the extent not already registered) with the United States Patent and Trademark Office or the United States Copyright Office, as applicable: (i) those intellectual property rights listed on Exhibits A, B and C hereto within thirty (30) days of the date of this Agreement; (ii) all registerable intellectual property rights Grantor has developed as of the date of this Agreement but heretofore failed to register, within thirty (30) days of the date of this Agreement; and (iii) those additional intellectual property rights developed or acquired by Grantor from time to time in connection with any product or service, prior to the sale or licensing of such product or the rendering of such service to any third party and prior to Grantor's use of such product (including without limitation revisions or additions to the intellectual property rights listed on such Exhibits A, B and C). Grantor shall, from time to time, execute and file such other instruments, and take such further actions as Secured Party may reasonably request from time to time to perfect or continue the perfection of Secured Party's interest in the Collateral. Grantor shall give Secured Party notice of all such applications or registrations;

(i) This Agreement creates, and in the case of after acquired Collateral, this Agreement will create at the time Grantor first has rights in such after acquired Collateral, in favor of Secured Party a valid and perfected first priority security interest in the Collateral in the United States securing the payment and performance of the obligations evidenced by the Loan Agreements;

(j) All information heretofore, herein or hereafter supplied to Secured Party by or on behalf of Grantor with respect to the Collateral is accurate and complete in all material respects;

(k) Grantor shall not enter into any agreement that would materially impair or conflict with Grantor's obligations hereunder without Secured Party's prior written consent, which consent shall not be unreasonably withheld. Grantor shall not permit the inclusion in any material contract to which it becomes a party of any provisions that could or might in any way prevent the creation of a security interest in Grantor's rights and interests in any property included within the definition of the Collateral acquired under such contracts; and

(l) Upon any executive officer of Grantor obtaining actual knowledge thereof, Grantor will promptly notify Secured Party in writing of any event that materially adversely affects the value of any Collateral, the ability of Grantor to dispose of any Collateral or the rights and remedies of Secured Party in relation thereto, including the levy of any legal process against any of the Collateral.

3. Secured Party's Rights. Secured Party shall have the right, but not the obligation, to take, at Grantor's sole expense, any actions that Grantor is required under this Agreement to take but which Grantor fails to take, after fifteen (15) days' notice to Grantor. Grantor shall reimburse and indemnify Secured Party for all reasonable costs and reasonable expenses incurred in the reasonable exercise of its rights under this section 3.

4. Inspection Rights. Grantor hereby grants to Secured Party and its employees, representatives and agents the right to visit, during reasonable hours upon prior reasonable written notice to Grantor, any of Grantor's plants and facilities that manufacture, install or store products (or that have done so during the prior six-month period) that are sold utilizing any of the Collateral, and to inspect the products and quality control records relating thereto upon reasonable written notice to Grantor and as often as may be reasonably requested.

5. Further Assurances; Attorney in Fact.

(a) On a continuing basis, Grantor will make, execute, acknowledge and deliver, and file and record in the proper filing and recording places in the United States, all such instruments, including appropriate financing and continuation statements and collateral agreements and filings with the United States Patent and Trademark Office and the Register of Copyrights, and take all such action as may reasonably be deemed necessary or advisable, or as requested by Secured Party, to perfect Secured Party's security interest in all Copyrights, Patents and Trademarks and otherwise to carry out the intent and purposes of this Agreement, or for assuring and confirming to Secured Party the grant or perfection of a security interest in all Collateral.

(b) Grantor hereby irrevocably appoints Secured Party as Grantor's attorney-in-fact, with full authority in the place and stead of Grantor and in the name of Grantor, from time to time in Secured Party's discretion, to take any action and to execute any instrument which Secured Party may deem necessary or advisable to accomplish the purposes of this Agreement, including (i) to modify, in its sole discretion, this Agreement without first obtaining Grantor's approval of or signature to such modification by amending Exhibit A, Exhibit B and Exhibit C, hereof, as appropriate, to include reference to any right, title or interest in any Copyrights, Patents or Trademarks acquired by Grantor after the execution hereof or to delete any reference to any right, title or interest in any Copyrights, Patents or Trademarks in which Grantor no longer has or claims any right, title or interest, (ii) to file, in its sole discretion, one or more financing or continuation statements and amendments thereto, relative to any of the Collateral without the signature of Grantor where permitted by law and (iii) after the occurrence of an Event of Default, to transfer the Collateral into the name of Secured Party or a third party to the extent permitted under the California Uniform Commercial Code.

6. Events of Default. The occurrence of any of the following shall constitute an Event of Default under the Agreement:

(a) An Event of Default occurs under the Loan Agreements; or

(b) Grantor breaches any warranty or agreement made by Grantor in this Agreement and, as to any breach that is capable of cure, Grantor fails to cure such breach within five (5) days of the occurrence of such breach.

7. Remedies. Upon the occurrence and continuance of an Event of Default, Secured Party shall have the right to exercise all the remedies of a secured party under the California Uniform Commercial Code, including without limitation the right to require Grantor to assemble the Collateral and any tangible property in which Secured Party has a security interest and to make it available to Secured Party at a place designated by Secured Party. Secured Party shall have a nonexclusive, royalty free license to use the Copyrights, Patents and Trademarks to the extent reasonably necessary to permit Secured Party to exercise its rights and remedies upon the occurrence of an Event of Default. Grantor will pay any expenses (including reasonable attorneys' fees) incurred by Secured Party in connection with the exercise of any of Secured Party's rights hereunder, including without limitation any expense incurred in disposing of the Collateral. All of Secured Party's rights and remedies with respect to the Collateral shall be cumulative.

8. Indemnity. Grantor agrees to defend, indemnify and hold harmless Secured Party and its officers, employees, and agents against: (a) all obligations, demands, claims, and liabilities claimed or asserted by any other party in connection with the transactions contemplated by this Agreement, and (b) all losses or expenses in any way suffered, incurred, or paid by Secured Party as

a result of or in any way arising out of, following or consequential to transactions between Secured Party and Grantor, whether under this Agreement or otherwise (including without limitation reasonable attorneys' fees and reasonable expenses), except for losses arising from or out of Secured Party's gross negligence or willful misconduct.

9. Course of Dealing. No course of dealing, nor any failure to exercise, nor any delay in exercising any right, power or privilege hereunder shall operate as a waiver thereof.

10. Attorneys' Fees. If any action relating to this Agreement is brought by either party hereto against the other party, the prevailing party shall be entitled to recover reasonable attorneys' fees, costs and disbursements.

11. Amendments. This Agreement may be amended only by a written instrument signed by both parties hereto.

12. Counterparts. This Agreement may be executed in two or more counterparts, each of which shall be deemed an original but all of which together shall constitute the same instrument.

13. California Law and Jurisdiction; Jury Waiver. This Agreement shall be governed by the laws of the State of California, without regard for choice of law provisions. Grantor and Secured Party consent to the exclusive jurisdiction of any state or federal court located in Santa Clara County, California. GRANTOR AND SECURED PARTY EACH WAIVE THEIR RESPECTIVE RIGHTS TO A JURY TRIAL OF ANY CLAIM OR CAUSE OF ACTION BASED UPON OR ARISING OUT OF THE LOAN AGREEMENTS, THIS AGREEMENT, OR ANY OF THE TRANSACTIONS CONTEMPLATED HEREIN, INCLUDING CONTRACT CLAIMS, TORT CLAIMS, BREACH OF DUTY CLAIMS, AND ALL OTHER COMMON LAW OR STATUTORY CLAIMS.

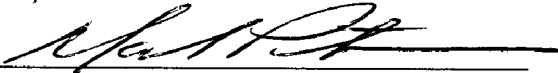
IN WITNESS WHEREOF, the parties hereto have executed this Agreement on the day and year first above written.

GRANTOR:

Address of Grantor:

400 Benjamin Lane  
Boise, ID 83704

SCP IP, INC.

By: 

Its: President + CEO

Attn: Chief Financial Officer

SECURED PARTY

Address of Secured Party:

9920 S. La Cienega Blvd., Suite 1401  
Inglewood, CA 90301

COMERICA BANK-CALIFORNIA

By: \_\_\_\_\_

Its: \_\_\_\_\_

Attn: Manager

a result of or in any way arising out of, following or consequential to transactions between Secured Party and Grantor, whether under this Agreement or otherwise (including without limitation reasonable attorneys' fees and reasonable expenses), except for losses arising from or out of Secured Party's gross negligence or willful misconduct.

9. Course of Dealing. No course of dealing, nor any failure to exercise, nor any delay in exercising any right, power or privilege hereunder shall operate as a waiver thereof.

10. Attorneys' Fees. If any action relating to this Agreement is brought by either party hereto against the other party, the prevailing party shall be entitled to recover reasonable attorneys' fees, costs and disbursements.

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12. Counterparts. This Agreement may be executed in two or more counterparts, each of which shall be deemed an original but all of which together shall constitute the same instrument.

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IN WITNESS WHEREOF, the parties hereto have executed this Agreement on the day and year first above written.

GRANTOR:

Address of Grantor:

SCP IP, INC.

400 Benjamin Lane  
Boise, ID 83704

By: [Signature]

Its: President and CEO

Attn: Chief Financial Officer

SECURED PARTY

Address of Secured Party:

COMERICA BANK-CALIFORNIA

9920 S. La Cienega Blvd., Suite 1401  
Inglewood, CA 90301

By: [Signature]

Its: VICE PRESIDENT

Attn: Manager

EXHIBIT A

Copyrights

Description

Registration Number

Registration Date

**EXHIBIT B**

Patents

<b>Prov./ U.S. Serial App. Numbers</b>	<b>Publication Number</b>	<b>Abbreviated Title</b>	<b>Full Title</b>	<b>Priority Date (Provisional Filing Date)</b>	<b>Date Filed</b>	<b>Inventor(s)</b>
09/478,094		Surfactant Clean	Method for Reducing Particle Contamination During the Wet Processing of Semiconductor Substrates	01/05/99	01/05/00	Verhaverbeke
60/135,267 09/574,790		Copper Cleaning with SC1/HF	Method for Wet Processing Electronic Components Having Copper Containing Surfaces	05/21/99	05/19/00	Verhaverbeke
60/168,487 09/727/661	US-2002-0066717-A1 on 6/6/2002	Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	12/02/99	12/01/00	Verhaverbeke & DiBello
09/930,009	US-2002-0104552-A1	Injection Tube Calibration	Systems and Methods for Forming Processing Streams	08/17/00	08/15/01	Kaiser & Bay
60/270,815 10/074,516	US-2002-0119245-A1	Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	02/23/01		Verhaverbeke
		Point of Use Chemical Generation with Gases				Walter
10/163,441 Prv'1 was 60/295,919	confirm No. 6959	Colorimetric Sulfuric Monitoring	Method and Systems for Monitoring Process Fluids	06/05/01	06/05/01	DiBello, Carter & Bowen
10/301,322		Improved Low Pressure IPA Drying	Apparatus and Methods for Drying Electronic Component Precursors		11/21/01	DiBello
10/299,308		PTFE Meg Carrier	Sonic Transducers bonded with Polymers and Methods of Making Same for Efficient Sonic Energy Transfer	11/19/01	11/19/01	Gottschalk and Hollweck
		Reduced Volume Clean	Systems and Methods for Cleaning Semiconductor Substrates Using a Reduced Volume of Liquid	03/11/02		Savas, Zajac, and Galewski



FOREIGN PATENTS

US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
6,261,845 B1	92922583.7		Methods for Treating Objects	Ultra Cleaning of Involutd Microparts	Europe	12/17/93	10/02/92	Walter
6,261,845 B1	98 20 3334.2			Method for Treating Objects	Europe	10/04/91	10/02/98	Walter
6,132,522	PCT/US97/1208 8 WO98/03273		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	PCT	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
6,132,522	97932574.3 97936936027.0 Pub.No. 0912259		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	EPO	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
6,132,522	10-1999-7000355		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	Korea	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
6,132,522	507004/98		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	Japan	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
5,972,123	PCT/US98/1231 0 WO98/56726		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	PCT	06/13/97	06/12/98	Verhaverbeke
5,972,123	98929046.5 Pub. No. 0989962		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	EPO	06/13/97	06/12/98	Verhaverbeke
5,972,123	98805967.3 Pub.No.CN1259 925A		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	China	06/13/97	06/12/98	Verhaverbeke
5,972,123	503284/99		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	Japan	06/13/97	06/12/98	Verhaverbeke
5,972,123	99-7010670		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	Korea	06/13/97	06/12/98	Verhaverbeke
09/209,101	PCT/US98/2611 8 WO99/30355		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	PCT	12/11/97	12/09/99	Verhaverbeke & McConnell
09/209,101	87120411		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Taiwan	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	98 8 08586.0 CN 1268244A		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	China	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	98962020.8 Pub. No. 1044465		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	EPO	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	524813/00		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Japan	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	2000-7005687		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Korea	12/11/97	12/01/98	Verhaverbeke & McConnell
09/324,813	PCT/US99/1214 4 WO99/62837		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	PCT	06/02/98	06/02/99	Verhaverbeke
09/324,813	99 8 06667.2		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	China	06/02/98	06/02/99	Verhaverbeke
09/324,813	99926113.4 Pub. No. 1082271		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	EPO	06/02/98	06/02/99	Verhaverbeke
09/324,813	PCT/US99/1214 4 552055/00		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	Japan	06/02/98	06/02/99	Verhaverbeke

US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
6,378,544 B1	PCT/US00/10590 WO 00/65266		Rupture Disks	Pressure Relief Device and Method of Using the Same	PCT	04/22/99	04/20/00	DiBello
6,378,544 B1	2001-7013323		Rupture Disks	Pressure Relief Device and Method of Using the Same	Korea	04/22/99	04/20/00	DiBello
6,378,544 B1	89107537		Rupture Disks	Pressure Relief Device and Method of Using the Same	Taiwan	04/22/99	04/21/00	DiBello
6,378,544 B1	928225.2		Rupture Disks	Pressure Relief Device and Method of Using the Same	Europe	04/23/99	04/22/00	DiBello
6,378,544 B1	613970/00		Rupture Disks	Pressure Relief Device and Method of Using the Same	Japan	04/22/99	04/20/00	DiBello
6,378,544 B1	806473.3		Rupture Disks	Pressure Relief Device and Method of Using the Same	China	04/22/99	10/19/01	DiBello
09/395,398	PCT/US99/21339 WO 00/15352		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	PCT	09/17/98	09/16/99	Verhaverbeke & McConnell
09/395,398	PCT/US99/21339 WO 00/15352 SN# 99 8 10935.5		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	China	09/14/99	3/ /01	Verhaverbeke & McConnell
09/395,398	99969047.2 Pub No 1115503		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	EPO	09/14/99	09/16/99	Verhaverbeke & McConnell
09/395,398	569928/00		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	Japan	09/14/99	3/ /01	Verhaverbeke & McConnell
09/395,398	PCT/US99/21339 WO 00/15352		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	Korea	09/14/99	3/ /01	Verhaverbeke & McConnell
60/135,267	PCT/US00/14019	1198620	Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	PCT	05/21/99	05/19/00	Verhaverbeke
60/135,267	936165		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	EPO			Verhaverbeke
60/135,267	00807855.6	CN 1352703A No. 23 Vol 18 patent gazette	Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	China	05/21/99	11/21/01	Verhaverbeke
60/135,267	620153/00		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	Japan	05/21/99	05/19/00	Verhaverbeke
	2001-7014820		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	Korea	05/21/99	05/19/00	Verhaverbeke
60/168,487	PCT/US00/42449 Pub#WO 01/40124		Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	PCT	12/02/99	12/01/00	Verhaverbeke & DiBello
60/168,487	89125686		Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	Taiwan	12/02/99	12/02/00	Verhaverbeke & DiBello
60/188,895	PCT/US01/07959		IPOZONIA	Processes and Apparatus for Treating Electronic Components	PCT	03/13/00	03/13/01	Verhaverbeke, Liu, Walter, Sheen & McConnell
60/188,895	90105810		IPOZONIA	Processes and Apparatus for Treating Electronic Components	Taiwan	03/13/00	03/13/01	Verhaverbeke, Liu, Walter, Sheen & McConnell
60/270,815	CFMT-0280		Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	Taiwan	02/23/01		Verhaverbeke
60/270,815	PCT/US02/04299		Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	PCT	02/23/01		Verhaverbeke
09/930,009	90120208		Injection Tube Calibration	Systems and Methods for Forming Processing Streams	Taiwan	08/17/00	08/15/01	Kaiser & Bay
09/930,009	PCT/US01/4172		Injection Tube Calibration	Systems and Methods for	PCT	08/17/00	08/15/01	Kaiser & Bay

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US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
	9			Forming Processing Streams				
60/295,919	PCT/US02/1770 3		Chemical End Life Monitoring	Methods and Systems for Monitoring Process Fluids	PCT	Method and Systems for Monitoring Process Fluids	06/04/02	DiBello, Carter & Bowen
60/295,919			Chemical End Life Monitoring	Methods and Systems for Monitoring Process Fluids	Taiwan	Method and Systems for Monitoring Process Fluids	06/04/02	DiBello, Carter & Bowen

	<u>U.S. Patent Number</u>	<u>Appl Number</u>	<u>Full Title</u>	<u>Date Filed</u>	<u>Date Issued</u>	<u>Date of Expiration</u>	<u>Inventor(s)</u>
1	4,577,650	612,355	Vessel and System for Treating Wafers with Fluids	05/21/84	03/25/86	03/25/03	McConnell
2	4,633,893	747,894	Apparatus for Treating Semiconductor Wafers	06/24/85	01/06/87	01/06/04	McConnell & Walter
3	4,738,272	747,895	Vessel and System for Treating Wafers with Fluids	06/24/85	04/19/88	04/19/05	McConnell
4	4,740,249	922,882	Vessel and System for Treating Wafers with Fluids	10/24/86	04/26/88	04/26/05	McConnell
5	4,778,532	765,294	Process and Apparatus for Treating Wafers with Process Fluids	08/13/85	10/18/88	10/18/05	McConnell & Walter
6	4,795,497	805,203	Method and System for Fluid Treatment of Semiconductor Wafers	12/04/85	01/03/89	01/03/06	McConnell & Walter
7	4,856,544	07/125,245	Vessel and System for Treating Wafers with Fluids	11/25/87	08/15/89	08/15/06	McConnell
8	4,899,767	/283,465	Method and System for Fluid Treatment of Semiconductor Wafers	12/12/88	02/13/90	02/13/07	McConnell & Walter
9	4,911,761	07/184,544	Process and Apparatus for Drying Surfaces	04/20/88	03/27/90	03/27/07	McConnell & Walter
10	4,917,123	07/252,823	Apparatus for Treating Wafers with Process Fluids	10/03/88	04/17/90	04/17/07	McConnell & Walter
11	4,984,597	/431268	Apparatus for Rinsing and Drying Surfaces	11/03/89	01/15/91	01/15/08	McConnell & Walter
12	5,383,484	08/093,116	Static Megasonic Cleaning System for Cleaning Objects	07/16/93	01/24/95	07/16/13	Thomas, Carolin, Erhardt & McConnell
13	5,972,123	09/096,898	Methods for Treating Semiconductor Wafers	06/12/98	10/26/99	06/12/18	Verhaverbeke
14	6,032,682	08/881,267	Method for Sulfuric Acid Resist Stripping	06/24/97	03/07/00	06/24/17	Verhaverbeke
15	6,132,522	08/684,543	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	07/19/96	10/17/00	07/19/16	Verhaverbeke, McConnell & Trissel
16	6,143,087	09/253,629	Methods for Treating Objects	02/19/99	11/07/00	02/19/19	Walter
17	6,165,912	09/395,398	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	09/14/99	12/26/00	09/14/19	McConnell & Verhaverbeke
18	6,245,158 B1	09/324,813	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperatures	06/02/99	06/12/01	06/19/19	Verhaverbeke
19	6,261,845 B1	09/257,488	Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates	02/25/99	07/17/01	02/25/19	Verhaverbeke, DiBello & McConnell
20	6,348,101	09/669/789	Methods for Treating Objects	09/26/00	02/19/02	09/26/20	Walter
21	6,378,544 B1	60/130,466 09/564,358	Pressure Relief Device and Method of Using the Same	04/22/99	04/30/02	04/22/19	DiBello
22	6,491,763	09/805,348	Process and Apparatus for Treating Electronic Components	03/13/01	12/10/02	03/13/21	Verherbeke, Liu, Walter, Sheen & McConnell
23	6,495,099	09/209,101	Wet Processing Methods for the Manufacture of Electronic Components	12/10/98	12/17/02	12/10/18	Verhaverbeke & McConnell

EXHIBIT C

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2 079 255	06/08/94	09/27/94	DE	<b>MARANGONI</b>	Kl.:9,11,37
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6 107 1996	11/15/94	11/01/96	DK		Kl.: 11, 37
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